

MA151A, MA152A

Silicon Epitaxial Planar Type

Switching

■ Features

- Fast t_{rr}
- Small C_t

■ Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

Item	Symbol	Value	Unit
Reverse Voltage (DC)	MA151A	40	V
	MA152A	80	
Peak Reverse Voltage	MA151A	40	V
	MA152A	80	
Forward Current (DC)	I_F	100	mA
Peak Forward Current	I_{FM}	225	mA
Non-Repetitive Peak Forward Surge Current	I_{FSM}^*	500	mA
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 ~ +150	$^\circ\text{C}$

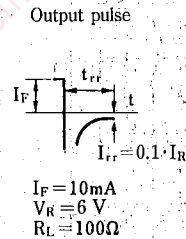
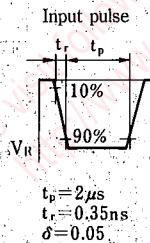
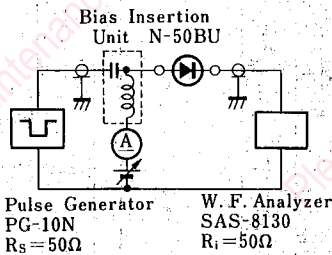
* $t=1\text{s}$

■ Electrical Characteristics ($T_a=25^\circ\text{C}$)

Item	Symbol	Condition	min.	typ.	max.	Unit
Reverse Current (DC)	MA151A	$V_R=35\text{V}$			0.1	μA
	MA152A	$V_R=75\text{V}$			0.1	
Forward Voltage (DC)	V_F	$I_F=100\text{mA}$			1.2	V
Reverse Voltage (DC)	MA151A	$I_R=100\mu\text{A}$	40			V
	MA152A		80			
Terminal Capacitance	C_t	$V_R=0, f=1\text{MHz}$			2	pF
Reverse Recovery Time	t_{rr}^*	$I_F=10\text{mA}, V_R=6\text{V}, R_L=100\Omega$ $I_{rr}=0.1 \cdot I_R$			3	ns

© Input and output frequency of ratings: 100MHz

* t_{rr} measuring circuit



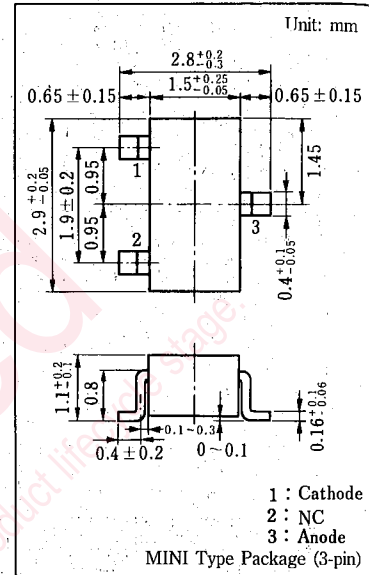
■ Marking Symbol

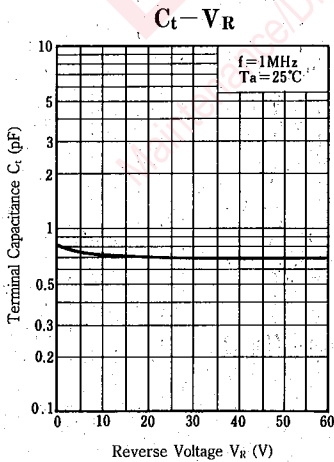
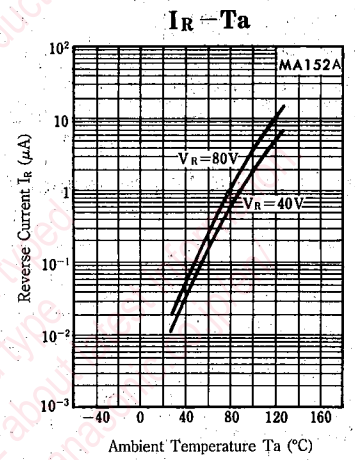
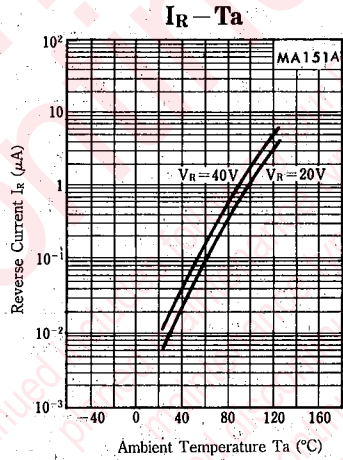
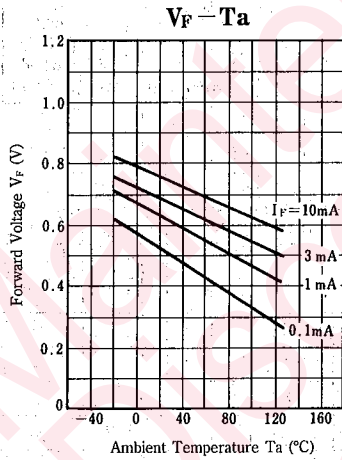
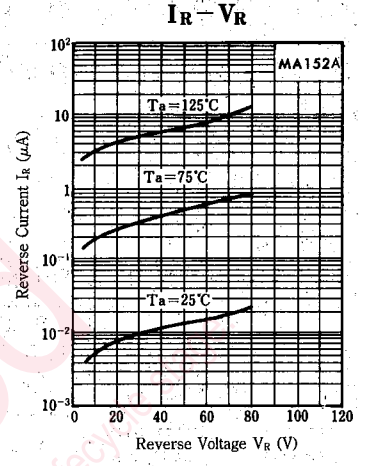
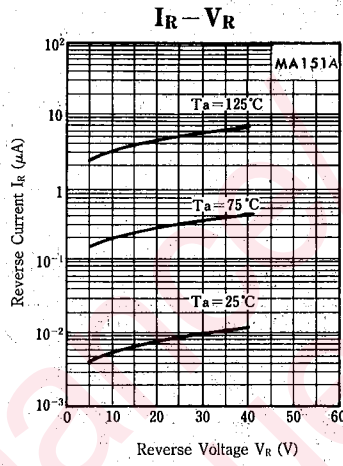
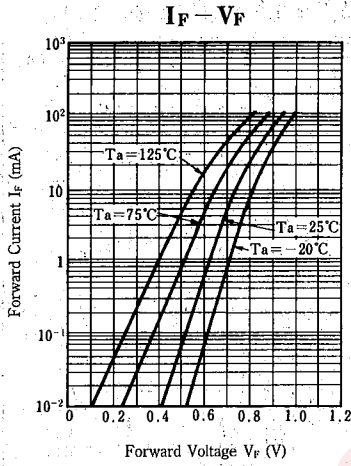
Type No.	MA151A	MA152A
Symbol	MA	MB

■ Marking Symbol (Ex.)



■ Package Dimensions





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